



Product/Process Change Notice - PCN 16_0234 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Assembly Transfer to ASE Korea and Test Transfer to STATS ChipPAC Singapore of Select LFCSP Parts.

Publication Date: 31-Oct-2016

Effectivity Date: 31-Oct-2016 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is transferring to subcontractor ASE Korea for assembly manufacturing and STATS ChipPAC Singapore for test manufacturing of select LFCSP products.

ADI has qualified ASE Korea's BOM(Bill of Materials). The mold compound is changing from Sumitomo G770 to Sumitomo G700. Die attach epoxy is changing from Able8290 and Able3230 to EN4900GC for 5x5 LFCSP devices. See BOM attachment for details.

The package outline exposed pad dimensions are changing for 3x3mm 8LD/16LD, 4x4mm 16LD/20LD/24LD, 5x5mm 28LD/32LD. See POD attachment for details.

Reason For Change

ADI's current Assembly and Test supplier STATS ChipPAC China is relocating their factory by end of September 2017.

In this regard, the affected products currently assembled and tested in that facility will be transferred to new Assembly and Test site to ensure continuous supply of products.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

There will be no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled and tested from the new site will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Results Summary. Test correlation will be performed and validated. See attached Test Correlation Plan.

Comments

During transition to new assembly and/or Test Site, products will be Assembled/or Tested from either current or new Assembly and/or Test Site. The customers may receive products that are assembled at AEK & tested at SCC and/or assembled at SCC & tested at STA. Applies for all packing/reel options.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_16_0234_Rev_-_Qual Results Summary for LFCSP.pdf

Attachment 2: Type: Detailed Change Description

ADI_PCN_16_0234_Rev_-_BOM Change Description.pptx

Attachment 3: Type: Detailed Change Description

ADI_PCN_16_0234_Rev_-_POD Change Description.pptx

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (78)

AD7172-4 / AD7172-4BCPZ	AD7172-4 / AD7172-4BCPZ-RL	AD7172-4 / AD7172-4BCPZ-RL7	AD7195 / AD42/334Z-0RL	AD7195 / AD7195BCPZ
AD7195 / AD7195BCPZ-RL	AD7195 / AD7195BCPZ-RL7	AD8659 / AD8659ACPZ-R7	AD8659 / AD8659ACPZ-RL	ADA4084-2 / ADA4084-2ACPZ-R7
ADA4084-2 / ADA4084-2ACPZ-RL	ADA4084-4 / ADA4084-4ACPZ-R7	ADA4084-4 / ADA4084-4ACPZ-RL	ADA4528-1 / ADA4528-1ACPZ-R7	ADA4528-1 / ADA4528-1ACPZ-RL
ADA4960-1 / ADA4960-1ACPZ-R7	ADA4960-1 / ADA4960-1ACPZ-RL	ADD5211 / ADD5211ACPZ-R7	ADD5211 / ADD5211ACPZ-RL	ADE7953 / ADE7953ACPZ
ADE7953 / ADE7953ACPZ-RL	ADE7978 / AD71162ACPZ-RL	ADE7978 / ADE7978ACPZ	ADE7978 / ADE7978ACPZ-RL	ADP1052 / ADP1052ACPZ-R7
ADP1052 / ADP1052ACPZ-RL	ADP1828 / ADP1828ACPZ-R7	ADP1851 / ADP1851ACPZ-R7	ADP1853 / ADP1853ACPZ-R7	ADP1876 / ADP1876ACPZ-R7
ADP2164 / ADP2164ACPZ-1.0-R7	ADP2164 / ADP2164ACPZ-1.2-R7	ADP2164 / ADP2164ACPZ-1.5-R7	ADP2164 / ADP2164ACPZ-1.8-R7	ADP2164 / ADP2164ACPZ-2.5-R7
ADP2164 / ADP2164ACPZ-3.3-R7	ADP2164 / ADP2164ACPZ-R7	ADP2165 / ADP2165ACPZ-1.0-R7	ADP2165 / ADP2165ACPZ-1.2-R7	ADP2165 / ADP2165ACPZ-1.5-R7
ADP2165 / ADP2165ACPZ-1.8-R7	ADP2165 / ADP2165ACPZ-2.5-R7	ADP2165 / ADP2165ACPZ-3.3-R7	ADP2165 / ADP2165ACPZ-R7	ADP2166 / ADP2166ACPZ-1.0-R7
ADP2166 / ADP2166ACPZ-1.2-R7	ADP2166 / ADP2166ACPZ-1.5-R7	ADP2166 / ADP2166ACPZ-1.8-R7	ADP2166 / ADP2166ACPZ-2.5-R7	ADP2166 / ADP2166ACPZ-3.3-R7
ADP2166 / ADP2166ACPZ-R7	ADP2311 / ADP2311ACPZ-1-R7	ADP2311 / ADP2311ACPZ-2-R7	ADP2311 / ADP2311ACPZ-3-R7	ADP2311 / ADP2311ACPZ-4-R7
ADP320 / ADP320ACPZ-110-R7	ADP320 / ADP320ACPZ331815R7	ADP322 / ADP322ACPZ-115-R7	ADP322 / ADP322ACPZ-135-R7	ADP322 / ADP322ACPZ-145-R7
ADP322 / ADP322ACPZ-155-R7	ADP322 / ADP322ACPZ-165-R7	ADP322 / ADP322ACPZ-175-R7	ADP322 / ADP322ACPZ-189-R7	ADP5040 / ADP5040ACPZ-1-R7
ADP5041 / ADP5041ACPZ-1-R7	ADP5042 / ADP50420001CPZR	ADP5042 / ADP50420002CPZR	ADP5042 / ADP50420003CPZR	ADP5042 / ADP5042ACPZ-1-R7
ADP5042 / ADP5042ACPZ-2-R7	ADP5043 / ADP5043ACPZ-1-R7	ADP8866 / ADP8866ACPZ-R7	ADP8870 / ADP8870ACPZ-R7	SSM2602 / SSM2602CPZ-REEL
SSM2602 / SSM2602CPZ-REEL7	SSM2603 / SSM2603CPZ-REEL	SSM2603 / SSM2603CPZ-REEL7		

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	31-Oct-2016	31-Oct-2016	Initial Release

Analog Devices, Inc.

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